



Status of Compact Processing Module



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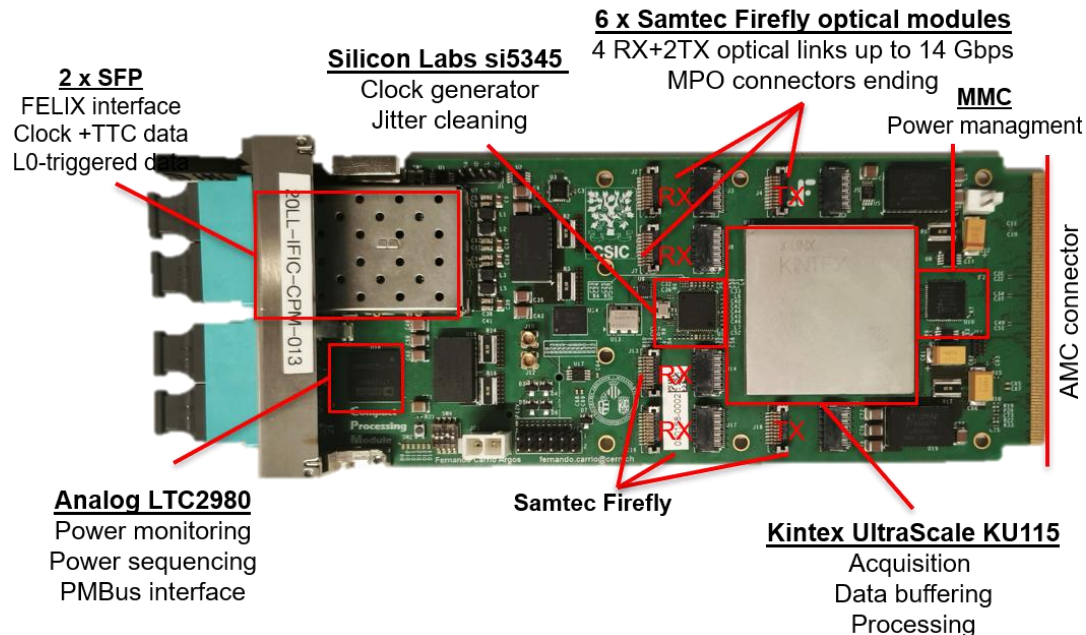
¹Instituto de Física Corpuscular (CSIC-UV)

23th September 2026

Valencia meeting



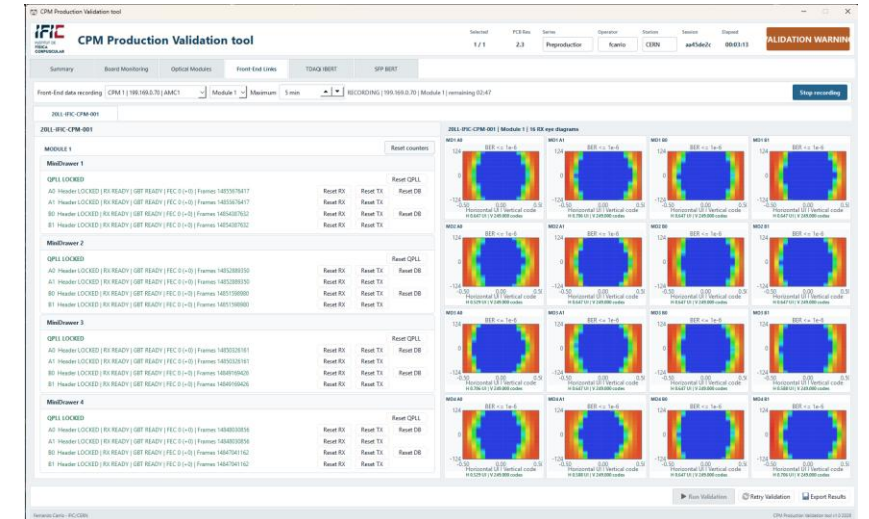
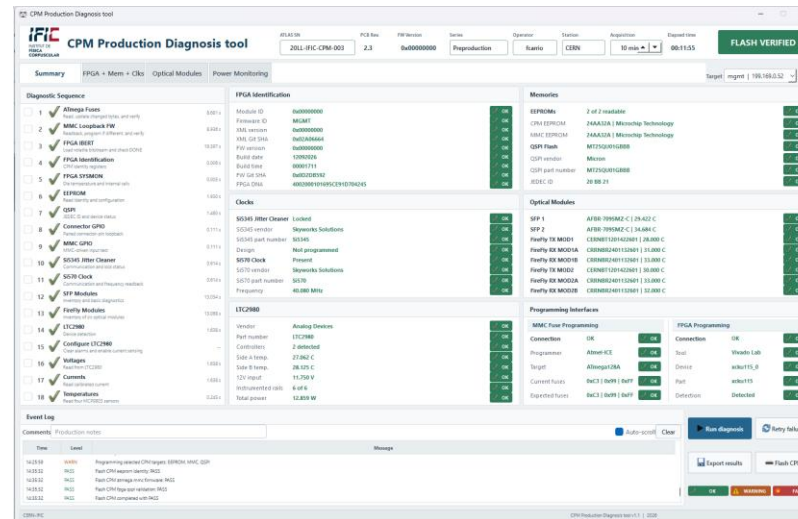
- Positive feedback from the Review Committee, with a few recommendations:
 - Connect the FPGA internal temperature diode to the MMC for monitoring
 - During QA and repair activities, perform the initial electrical and functional tests before installing the optical FireFly modules, minimizing the risk of damage if rework is required
 - Electrical FireFly modules can be used during this initial validation stage
- Updates before production
 - Add an IC to read the FPGA temperature diode from the MMC
 - Evaluate an extension of the MMC diode test pads
 - Evaluate replacement of the MMC programming connector with a larger-pitch version to facilitate access and handling



Production Preparation and Current Status



- Hardware
 - 2 CPMs to be repaired: One is an assembly problem, second the Atmega was burnt during tests
 - Layout revision for CPM production: approximately 1 month
 - Followed by a short pre-production batch of 4 CPMs with FPGA speed grade -2
 - ProDesign is currently the most likely option for the next manufacturing/assembly stage
- Test stations
 - A new CPM test box is being assembled with a new PCB design
 - Allow validation of all TDAQi links and debug potential problems with links during the diagnostics/validation test stage
 - Minor modifications at the software level
- Others
 - Preparation for shipping the current CPMs back to Valencia is complete, including the required paperwork



A photograph of a server rack. The rack is filled with various network equipment, including switches and routers. The equipment is illuminated with blue and green lights. A blue Ethernet cable is plugged into one of the ports. The text 'THANK YOU FOR YOUR ATTENTION!' is overlaid in red, bold, capital letters across the center of the image.

**THANK YOU FOR YOUR
ATTENTION!**